

**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®



**SSOP 16**  
CASE 565AE-01  
ISSUE O

DATE 19 SEP 2008

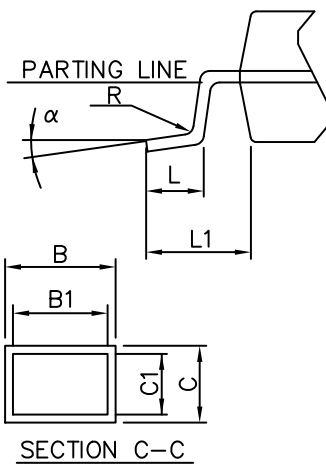
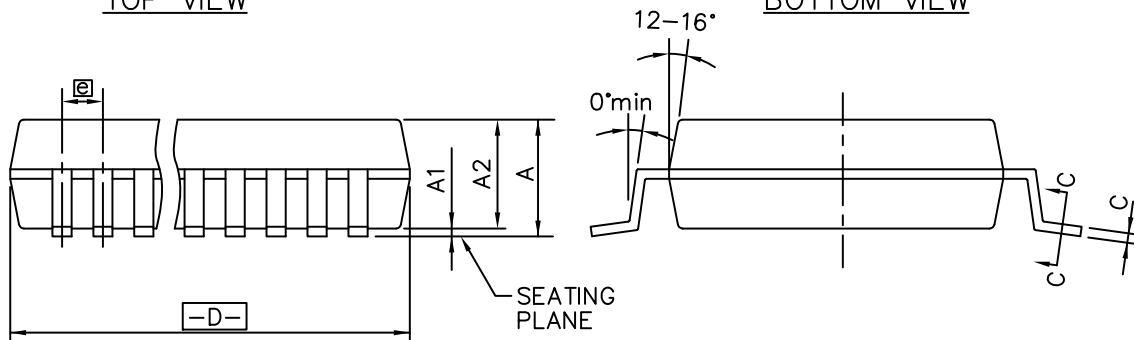
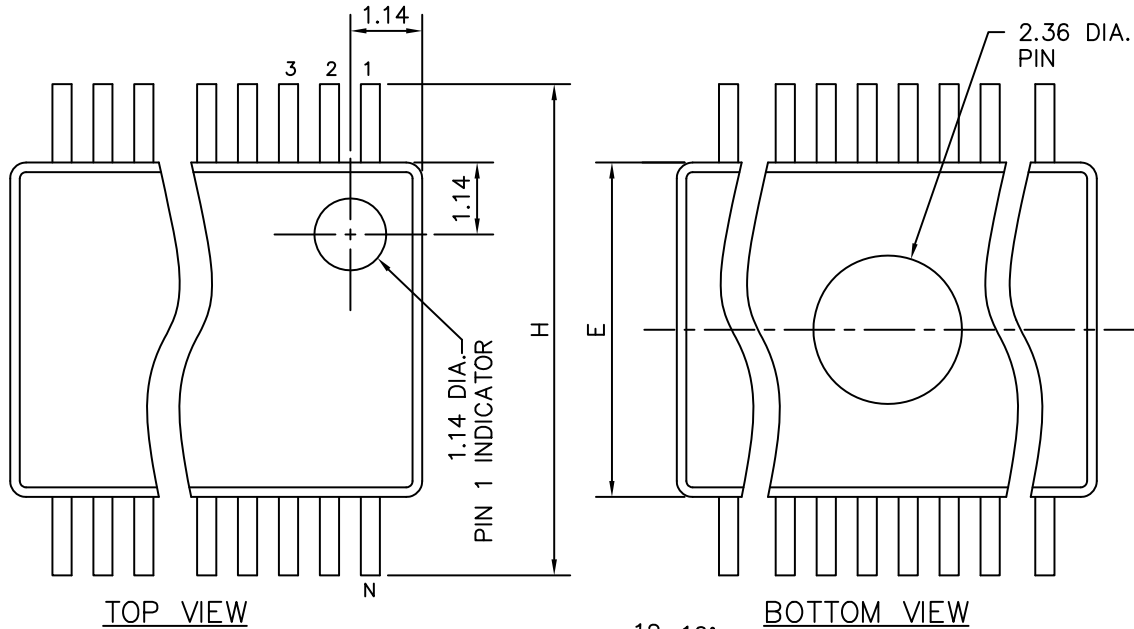


TABLE IN MILLIMETERS

SYMBOL	COMMON DIMENSIONS			NOTE VARIATIONS	1			2
	MIN.	NOM.	MAX.		D			N
A	1.73	1.86	1.99		2.87	3.00	3.13	8
A <sub>1</sub>	0.05	0.13	0.21	AA	6.07	6.20	6.33	14
A <sub>2</sub>	1.68	1.73	1.78	AB	6.07	6.20	6.33	16
B	0.25	—	0.38	AC	7.07	7.20	7.33	20
B <sub>1</sub>	0.25	0.30	0.33	AD	8.07	8.20	8.33	24
C	0.09	—	0.20	AE	10.07	10.20	10.33	28
C <sub>1</sub>	0.09	0.15	0.16	AF	10.07	10.20	10.33	30
D	SEE VARIATIONS			1				
E	5.20	5.30	5.38					
e	0.65 BSC							
H	7.65	7.80	7.90					
L	0.63	0.75	0.95					
L <sub>1</sub>	1.25 REF.							
N	SEE VARIATIONS			2				
α	0°	4°	8°					
R	0.09	0.15	—					

**NOTE:**  
MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.20mm on D PER SIDE.

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<b>DESCRIPTION:</b>	<b>SSOP 16</b>	<b>PAGE 1 OF 2</b>

